



More details here

CloudDC SuperServer SYS-611C-TN4R

Key Applications

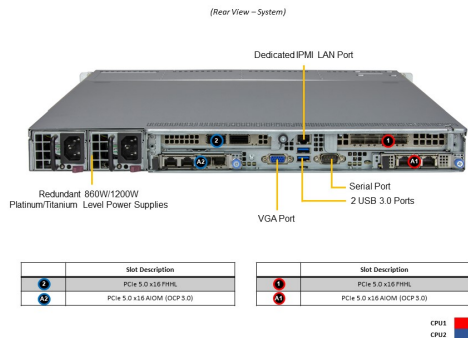
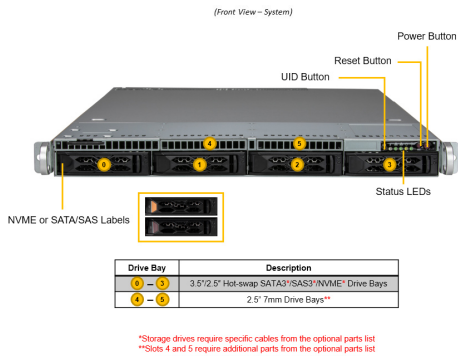
Web Server, Firewall Application, Data Center Optimized, Value IaaS, Cloud Computing, Compact Server, DNS & Gateway Servers, Firewall Application, CDN, Edge Nodes,

Key Features

- Dual sockets E (LGA-4677) 4th Gen Intel® Xeon® Scalable processors;
- 16 DIMMs up to 4TB 3DS ECC DDR5-4800: RDIMM;
- 2 PCIe 5.0 x16 FHHL; 2 PCIe 5.0 x4 NVMe M.2;
- Dual AIOM (OCP 3.0) slots with NCSI for networking, 1 dedicated IPMI LAN;
- 4x 3.5/2.5" hot-swap hybrid NVMe/SATA/SAS drive bays;
- 6 counter-rotating 4 cm PWM fans with optimal fan speed control, 2 air shrouds;
- 860W redundant Platinum level 100-240Vac and 200-240 Vdc power supplies;
- 1 VGA, 1 COM, 2 USB 3.0 (rear);



Form Factor	1U Rackmount Enclosure: 437 x 43 x 650mm (17.2" x 1.7" x 25.6") Package: 605 x 197 x 878mm (23.8" x 7.8" x 34.6")
Processor	4th Gen Intel® Xeon® Scalable processors Dual Socket LGA-4677 (Socket E) supported 4 UPI (Certain high TDP CPUs have support conditions. Contact Technical Support or Representative for details, Supports up to 270W TDP CPUs (Air Cooled))
System Memory	16 DIMM slots Up to 4 TB ECC RDIMM, DDR5-4800MHz
Drive Bays	4x 3.5" hot-swap NVMe/SATA/SAS drive bays (4x 3.5" NVMe hybrid)(Storage drives require additional cables from the optional parts list.) 2 M.2 NVMe M-Key, 2280
Expansion Slots	2 PCIe 5.0 x16 FHHL slot(s)
On-Board Devices	SATA: SATA3 (6Gbps); RAID 0/1/5/10 support NVMe: NVMe; RAID 0/1/5/10 support ((*VROC is required)) Chipset: Intel® C741 Network Connectivity: with Advanced IO Module, AIOM (OCP 3.0 NIC, refer to AIOM Network Card(s) under Optional Parts List for options) Note: High TDP 200-400G NICs have support conditions due to thermal requirements. IPMI: Support for Intelligent Platform Management Interface v.2.0 IPMI 2.0 with virtual media over LAN and KVM-over-LAN support
Input / Output	LAN: 1 Dedicated IPMI LAN port USB: 2 USB 3.0 port(s) (2 rear) Video: 1 VGA port(s) Serial Port: 1 COM Port(s) (1 rear)



System Cooling	6x 4cm heavy duty fan(s)
Power Supply	800W/860W 1U redundant power supply Dimension (W x H x L): 54.5 x 40.25 x 322 mm Output Type: Backplanes (gold finger)
System BIOS	BIOS Type: AMI 32MB SPI FLASH ROM
Management	SuperDoctor® 5; Watch Dog; NMI; SUM; KVM with dedicated LAN; SPM; Intel® Node Manager; SSM; IPMI 2.0; Redfish API; SCC
PC Health Monitoring	FAN: Fans with tachometer monitoring Status monitor for speed control Pulse Width Modulated (PWM) fan connectors Temperature: Monitoring for CPU and chassis environment Thermal Control for fan connectors CPU: Monitors for CPU Cores, Chipset Voltages, Memory. 8 Phase-switching voltage regulator
Dimensions and Weight	Height: 1.7" (43 mm) Width: 17.2" (437 mm) Depth: 25.6" (650 mm) Gross Weight: 41.5 lbs (18.8 kg) Net Weight: 25.5 lbs (11.6 kg) Packaging: 7.8" (H) x 23.8" (W) x 34.6" (D) Available Color: Black front & silver body
Operating Environment	Operating Temperature: 10°C ~ 35°C (50°F ~ 95°F) Non-operating Temperature: -40°C to 60°C (-40°F to 140°F) Operating Relative Humidity: 8% to 90% (non-condensing) Non-operating Relative Humidity: 5% to 95% (non-condensing)
Motherboard	Super X13DDW-A
Chassis	CSE-LA15TQC-R860AW2